

PRODUCT FEATURES

- Designed to the Intel spec. for supporting next generation Intel processor and Pentium-pro's with 2.5V clocking requirements with the Intel 440FX chipset.
- 4 host (CPU) clocks.
- IOAPIC for multiprocessing.
- Power management for Mobile applications.
- < 250 pS skew on CPU buffers</p>
- < 250 pS skew on PCI buffers</p>
- 48 Pin SSOP package for minimum board space

BLOCK DIAGRAM XIN
SEL1 SEL0 POWER CPU_en PWR_DWN# PLL2 PLL2 A8 MHZ 8 MHZ

	FREQUENCY TABLE										
STM	SEL1	SEL0	CPU	PCI							
Х	0	0	Tristate	Tristate							
0	0	1	63.0	31.5							
0	1	0 🥢	69.87	34.94							
Х	1		XIN/2	XIN/4							
1	0	1	60	30							
1	1	U	F44	33.22							

X = Don't Ca

RE 7	48 VDD 47 REF2 46 VDDq2 45 IOAPIC 44 VSS 43 VSS 42 CPUCLK0 41 CPUCLK1 40 VDDq2 39 CPUCLK2 38 CPUCLK3 37 VSS 36 8 MHZ 35 n/c 34 VDDq3 33 24 MHZ 32 VSS 31 STM
PCICLK7 = 17	32 VSS
n/c	29 CPU_en 28 PWR_DWN# 27 SEL0 26 SEL1 25 VDD



PIN DESCRIPTION

XIN, XOUT - These pins form an on-chip reference oscillator when connected to terminals of an external parallel resonant crystal (nominally 14.318 MHz). XIN may also serve as input for an externally generated reference signal.

SEL(0:1) - Standard frequency select inputs. They have internal pull-ups.

CPUCLK(0:3) - Low skew (<250 pS) clock outputs for host frequencies such as CPU, Chipset, Cache. VDDq2 is the supply voltage for these outputs.

PCICLK(0:7) - Low skew (<250pS) clock outputs for PCI frequencies. They are synchronous to CPUCLK's.

REF(0:2) - Buffered outputs of reference 14.3 MHz.

IOAPIC - Buffered output of 14.3 MHz for multiprocessor support. It is powered by VDDq2.

48 MHz - Frequency output for USB.

24 MHz - Frequency output for super I/O.

8 MHz - 8 MHz output frequency.

PWR_DWN# - Power down pin to turn the power of the whole chip down including the VCOs and the crystal buffer. It has an internal Pull-Up

CPU_en - Active low signal to stop the CPU clocks when low. It is high in national operation and has an internal Pull-Up.

PCI_en - Active lov signal stop the CI clocks, when low. It is high in ormal ope tion id has an internal Pull-Up.

STM - System test moo. Increased PCI and CPU clocks y 4.75% for system timing testing when low.

VSS - read pins for the chip.

VDD - Pow ply pins for analog and core circuitry.

Da4 - wer supply pins for 3.3V for PCI bus.

VDD 3 - Power supply pins for 3.3V IO pins.

IDDq2 - Power supply pins for 2.5V/3.3V IO pins.

N/C - No connection pins.

	TION TABLE										
SEL1	SEL0	CPU	PC	REF(0:2)	IOAPIC	24 MHz	48 MHz	8 MHz			
0	0	Trietata	i tate	Tristate	Tristate	Tristate	Tristate	Tristate			
0	1	√ote1	Note	14.318 MHz	14.318 MHZ	24 MHZ	48 MHZ	8 MHZ			
1	0	Note1	ote1	14.318 MHZ	14.318 MHZ	24 MHZ	48 MHZ	8 MHZ			
1	1	'IN/2	JN/4	XIN	XIN	XIN/4	XIN/2	XIN/12			

Note1: See Frequency, , Page 1



POWER MANAGEMENT FUNCTIONS

The IMISC672 clocks may be disabled according to the following table in order to reduce power consumption. All clocks are stopped in the low state. All clocks maintain a valid high period on transitions from running to stopped. On low to high transitions of PWR_DWN#, external circuitry should allow 2-3 mS for the VCOs to stabilize prior to releasing PCI_en or CPU_en to a high level. The CPU and PCI clocks transition between running and stopped following the latency table bellow. CPU and PCI clocks are stopped after a complete period in their low state.

CPU_en	PCI_en	PWR_DWN#	CPUCLK	PCICLK	OTHER Collis	XTAL & VCOs
Х	Х	0	LOW	LOW	LO.	OFF
0	0	1	LOW	LOW	P' NNN	RU'NING
0	1	1	LOW	Note2	UNNING	「」NNING
1	0	1	Note2	LOW	h NNING	RUNNING
1	1	1	Note2	Note2	RUi 'ING	RUNNING

Note2: See Frequency Table, Page 1

Signal	Signal State	Min Pulse Width	Mir. ate .y	Max Latency
		(count by clocks)	(count by C clock,	(count by CPU clocks)
CPU_en	0 (disabled)	100 CPU	1	4
	1 (enabled)	10 CPU	1	4
PCI_en	0 (disabled)	10 PCI		4
	1 (enabled)	10 PCI	2	4
PWR_DWN#	0 (power off)	3mS	1	4
	1 (normal)	3mS	2 mS	3 mS

.AXIN JM RATINGS

Voltage Relative to 'CO. -0.3V

Voltage Relative VDD: 0.3V

Storage Temper Jre: -65°C to + 150°C

Operating Temper Jre: -0°C to + 70°C

Maximum Power Suppry. 7V

This device contains circuitry to protect the inputs against damage due to high static voltages or electric field; however, precautions should be taken to avoid application of any voltage higher than the maximum rated voltages to this circuit. For proper operation, Vin and Vout should be constrained to the range:

VSS<(Vin or Vout)<VDD

Unused inputs must always be tied to an appropriate logic voltage level (either VSS or VDD).



ELECTRICAL CHARACTERISTICS										
Characteristic	Symbol	Min	Тур	Max	Units	Conditions				
Input Low Voltage	VIL	-	-	0.8	Vdc	-				
Input High Voltage	VIH	2.0	-	-	Vdc	-				
Input Low Current	IIL			-66	μA					
Input High Current	IIH			5	μA					
Output Low Voltage	VOL	-	-	0.4	Vdc	All Outputs (see switching spec)				
IOL = 12 mA										
Output High Voltage	VOH	2.4	-	-	Vdc	All Outputs see switching spec)				
IOH = 12 m A										
Tri-State leakage Current	loz	-	-	10	μA					
Dynamic Supply Current	IDD	-	40	90	mA	U = 66.6 N₁ 7 No Load				
Static Supply Current	IDD	-	20	30	mA	CPU 66.6 MHZ, No Load				
Short Circuit Current	ISC	25		-	mA	1 output at a time - 30 seconds				
	VDD = VDDq2 = VDDq3 VDDq4 3.3V+5%, TA = 0°C to +70°C									

	SWITCHING CHARACI. RISTIC									
Characteristic	Symbol	Min	Тур	Max	Un	Conditions				
Output Duty Cycle	-	45	5(55	%	See note 3				
CPUCLK(0:3) High Time	tHKH	5.2		- /	nS	@ 66.6 MHZ, Measured at 2.0V				
CPUCLK(0:3) Low Time	tHKL	<i>"</i> ປ	-		nS	@ 66.6 MHZ, Measured at 0.4V				
CPUCLK(0:3) High Time	tHKH	0		-	nS	@ 60 MHZ, Measured at 2.0V				
CPUCLK(0:3) Low Time	tHKI	5.8	-	-	nS	@ 60 MHZ, Measured at 0.4V				
CPU to PCI Offset	t/ F	1		4	nS	See Note 3				
Buffer out Skew All CPU and PCI Buffer Outputs	te FW	-	-	250	pS	See Note 3				
ΔPeriod Adjacent Cycle		 	-	<u>+</u> 250	pS	-				
Jitter Aboslute, CPU	tja			500	pS	(long term jitter measured over a 3 minute period)				
Overshoot/Undershoot Beyond Power Rails	V ,er	-	-	1.5	V	22 ohms @ source of 8 inch PCB run to 15 pf load				
Ring Back Exclusion	V_{RBE}	0.7		2.1	V	See Note 4				
VDD = VDD q3 = VDD q4 = 3.3 V $\pm 5\%$, VDD q2 = 2.375 V to 2.9 V , TA = 0 $^{\circ}$ C to +70 $^{\circ}$ C										

Note 3: CPUCLK(0:3) are measured at 1.25 V. All other signals are measured at 1.5V.

Note 4: Ring Back must not enter this range.



TYPE TB4L BUFFER CHARACTERISTICS FOR CPUCLK(0:3) and IOAPIC										
Characteristic	Symbol	Min	Тур	Max	Units	Conditio				
Pull-Up Current Min	IOH _{min}	22	-	-	mA	Vc∴t = 1.25 V				
Pull-Up Current Max	IOH _{max}	13	-	-	mA	Vc. = Vdda2 - 0.5V				
Pull-Down Current Min	IOL _{min}	50	-	-	mA	Vout 1.5 V				
Pull-Down Current Max	IOL _{max}	18	-	-	mA	/ _it = 0.4 V				
Rise/Fall Time Min	TRF	0.4	-	1.8	าร	20 pF Load				
Between 0.4 V and 2.0 V										
Rise/Fall Time Max	TRF _{max}	-	-	2.3	ı nS	20 pF Load				
Between 0.4 V and 2.0 V					ı					

 $VDD = VDDq3 = VDDq4 = 3.3V \pm 5\%$ $VDF_q2 = 2.375V \text{ to } 2.9V, TA = 0°C \text{ to } +70°C$

TYPE TB5L BUFFER CHARACTERICTICS FOR REF(1:2) and 48/24 MHZ

Characteristic	Symbol	Min	іур	_Max	nitsر	Conditions
Pull-Up Current Min	IOH _{min}	30	-	<u> </u>	mA	Vout = 1.5 V
Pull-Up Current Max	IOH _{max}	13	-	-	mA	Vout = Vdd-0.5V
Pull-Down Current Min	IOL _m	32		-	mA	Vout = 1.5 V
Pull-Down Current Max	IOL _×		-	29	mA	Vout = 0.4 V
Rise/Fall Time Min Between 0.4 V and 2.4 V	TRF _{mirr}	1.0	-	-	nS	20 pF Load
Rise/Fall Time Max Between 0.4 V and 2.4 V	TF -	-	-	4.0	nS	20 pF Load

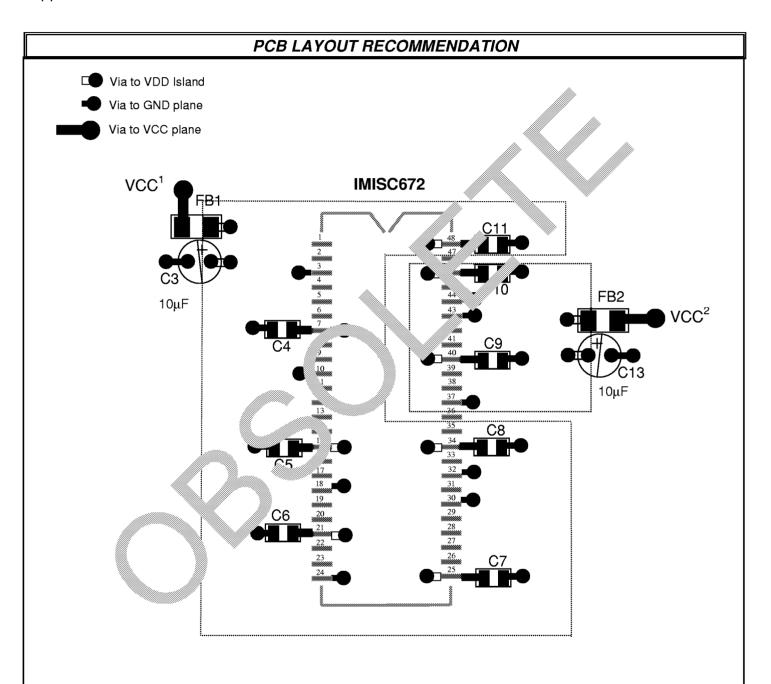
 $V\Gamma$ = $VDDq3 = VDDq4 = 3.3V \pm 5\%$, VDDQ2 = 2.375V to 2.9V, $TA = 0^{\circ}C$ to $+70^{\circ}C$

TYPE 34L BUFFER CHARACTERISTICS FOR REF0 and PCI								
Characteristic	Symbol	Min	Тур	Max	Units	Conditions		
Pull-Up Current Min	IOH _{min}	44	-	-	mA	Vout = 1.5 V		
Pull-Up Current Max	IOH _{max}	18	-	-	mA	Vout = Vdd-0.5V		
Pull-Down Current Min	IOL _{min}	50	-	-	m A	Vout = 1.5 V		
Pull-Down Current Max	IOL _{max}	18	-	-	m A	Vout = 0.4 V		
Rise/Fall Time Min Between 0.4 V and 2.4 V	TRF _{min}	0.5	-	1.4	nS	30 pF Load		
Rise/Fall Time Max Between 0.4 V and 2.4 V	TRF _{max}	-	-	2.4	nS	30 pF Load		

 $VDD = VDDq3 = VDDq4 = 3.3V \pm 5\%$, VDDq2 = 2.375V to 2.9V, $TA = 0^{\circ}C$ to $+70^{\circ}C$





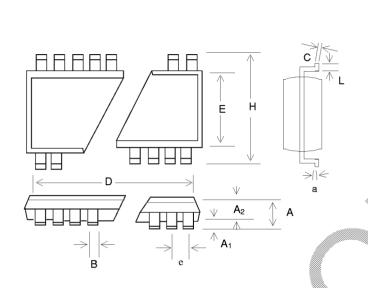


This is only a layout recommendation for best performance and lower EMI. The designer may choose a different approach but C4, C5, C6, C7, C8, C9, C10, and C11 (all are $0.1\mu f$) should always be used and placed close to their VDD pins.





PACKAGE DRAWING AND DIMENSIONS



48 PI	N SSC	P OU	TL'NE	DIMEI	NSION	IS
		INCH	MILLIMETERS			
SYMBOL	MIN	NO.	MA'	MIN	NOM	MAX
Α	0.095	ົ່ງ.102	i10	2 .	2.59	2.79
A ₁	0.00	0.012	0. 3	ົ້ນ.20	0.31	0.41
A2	(88	190	0.092	2.24	2.29	2.34
В	0.008	0.0	0.0135	0.203	0.254	0.343
С	0.005	-	0.010	0.127	-	0.254
	r_20	0.625	0.630	15.75	15.88	16.00
E	ა.292	296	0.299	7.42	7.52	7.59
e		J.025 BS0		C	.635 BS	O
Н	ر ا	0.406	0.410	10.16	10.31	10.41
a	0.10	0.013	0.016	0.25	0.33	0.41
L	0.024	0.032	0.040	0.61	0.81	1.02
	0.085	0.093	0.100	2.16	2.36	2.54

ORDERING INFORMATION		
Part Number	Package Type	Production Flow
IMISC672AYB	48 PIN 🐸 🤼	ommercial, 0°C to +70°C

Note: The ordering park simble is to ned by a combination of device number, device revision, package style, and screening as shown w.

Marking: Example: IMI

SC672A ' Date Cod Lot #

IMISC672 'B

B = Commercial, 0°C to + 70°C

<u>Package</u> Y = SSOP

Revision

IMI Device Number